REV LETTER: E PAGE NO: 1 OF 1 PART NUMBER:

Polymer PTC Devices

Surface mount fuses

Shanghai Wayon Thermo/Electro Materials Co.,Ltd.

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LP-SM125

Features

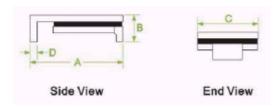
- □ Small size of 1812
- □ Fast tripping resettable circuit protection
- □ Surface mount packaging for automated assembly
- ☐ Agency Recognition: UL、CSA、TUV



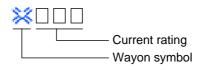


Product Dimensions (mm)

Part number -	Α	В	С	D
	Max	Max	Max	Max
LP-SM125	7.98	3.00	5.00	0.70



Part Marking System



Electrical Characteristics

Dowt washes	I _H	Ι _τ	V_{max}	I _{max}	T _{trip}		Pd _{typ}	R_{min}	R _{1max}
Part number	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-SM125	1.25	2.50	15	40	8.0	2.0	1.6	0.070	0.250

 I_H =Hold current: maximum current at which the device will not trip at 25 $\,$ still air.

I_T=Trip current: minimum current at which the device will always trip at 25 still air.

 V_{max} =Maximum voltage device can withstand without damage at rated current.

 I_{max} =Maximum fault current device can withstand without damage at rated voltage.

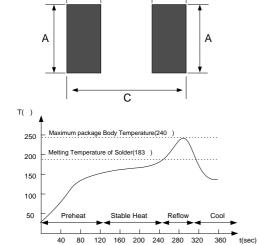
T_{trip}=Maximum time to trip(s) at assigned current.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 prior to tripping.

 $R_{1\text{max}}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number -	Α	В	С
Part Humber	(mm)	(mm)	(mm)
LP-SM125	3.1	2.3	9.7

- * Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.
- * Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.